US-PGUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGUB; EPO; JPO; DERWENT; USPAT; USPAT	L Number	Hits	Search Text	DB	Time stamp
EPO; JPO; DRRMENT; LINE TUBE 1	1	1779	(438/612).ccls. and @ad<=20020109		2003/01/23 08:47
2	İ.				
1 bond adj pad with copper with 'Al' and USFAT; US-PGEUB; EPO; JPO; DERWENT; TEM TOB USFAT; US-PGEUB; EPO; JPO; DERWENT; TEM TOB USFAT; US-PGEUB; EPO; JPO; DERWENT; TEM TOB USFAT; US-PGEUB; EPO; JPO; DERWENT; USFAT; U		•			
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EPO: JPO: DERMENT: IBM TOB USFAT: US-PCPUB: EPO: JPO: DERMENT: IBM TOB USFAT: U	2	1			2003/01/23 08:46
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buffer' US-PGFUB; PPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO;	1	1		IBM_TDB	
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DERMENT: IBM TOB		1	buffer		
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108-PCPUB; EPC; JPO; DERMENT; IBM TDB USPAT; US-PCPUB; EPC; JPO; JPO; DERMENT; IBM TDB USPAT; US-PCPUB; EPC; JPO; JPO; DERMENT; IBM TDB USPAT;		1		'IBM_TDB	
Total Tota	4	284	(438/48).ccls. and @ad<=20020109		2003/01/23 08:47
1722 (438/614).ccls. and @ad<=20020109 USPĀT; LSP-GEQUS; EPO; JPO; DENNERT; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-GEQUS; LSP-G	;			•	!
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Separate Separate	7	1722	(438/614).ccls. and @ad<=20020109		12003/01/23 10:35
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1222 1222 (257/784).ccls. and @ad<=20020109 DERWENT; IBM TOB SEPC; JPO; DERWENT; IBM TOB USPĀT;					
PRO; DOC DERWENT; IBM_TDB USPAT;	8	573	(257/459).ccls. and @ad<=20020109		2003/01/23 08:49
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;					
1		1			
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;		 			
10	9	1222	(257/784).ccls. and @ad<=20020109		2003/01/23 10:37
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	: !	I			1
10				t contract of the contract of	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; USPĀT; USPĀT	!				1
11	10	1209	(257/786).ccls. and @ad<=20020109		2003/01/23 08:51
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US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB;				1	
1392 (257/774).ccls. and @ad<=20020109 DERMENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM_TDB USPAT;	11	735	(257/781-782).ccls. and @ad<=20020109	USPĀT;	2003/01/23 08:52
1392 (257/774).ccls. and @ad<=20020109 DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM TDB USPAT; US-PGPUB; EPO; JPO; DPO; DPO; JPO; DPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J					
1392 (257/774).ccls. and @ad<=20020109 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;		+			i
13					•
13	12	1392	(257/774).ccls. and @ad<=20020109		2003/01/23 11:44
1					
13 1 'bond pad' with 'copper' with 'Al' and 'USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; With 'Al' With 'Al' USPAT; US-PGPUB; EPO; JPO; USPAT;					!
'buffer' 14				IBM_TDB	
14	13	1			2003/01/23 08:55
14 1 'bonding pad' with 'copper' with 'Al' and 'bonding pad' with 'Cu' with 'Al' and 'bonding pad' with 'Cu' with 'Al' DERWENT; SPGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; USPAT;			'builer'		i :
14 1 'bonding pad' with 'copper' with 'Al' and 'USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; With 'Al' USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO;					I.
'buffer' 'buffer' 'buffer' 'buffer' 'buffer' 'buffer' 'buffer' 'buffer' 'buffer' US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; With 'Al' 'buffer' US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; 'buffer' US-PGPUB; EPO; JPO; 'buffer' US-PGPUB; EPO; JPO;				IBM TDB	İ
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; With 'Al' US-PGPUB; EPO; JPO;	14	1		USPĀT;	2003/01/23 08:56
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; EPO; JPO; With 'Al' US-PGPUB; EPO; JPO;			'burier'	· ·	
15					
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; With 'Al' US-PGPUB; EPO; JPO;				IBM_TDB	
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	15	122	'bonding pad' with 'Cu' with 'Al'		2003/01/23 09:05
DERWENT; IBM_TDB USPAT; With 'Al' DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;				•	
16 117 @ad<=20020109 and 'bonding pad' with 'Cu' IBM_TDB USPAT; US-PGPUB; EPO; JPO;					!
with 'Al' US-PGPUB; EPO; JPO;					1
EPO; JPO;	16	117			2003/01/23 09:01
			with 'Al'		
1 DTT/AADTA1 1					1
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29	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	: 2003/01/23 09:03
	i	with 'Al'	US-PGPUB;	1
1	i		EPO; JPO;	:
	'		DERWENT;	:
			IBM_TDB	
30	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/01/23 09:05
		with 'Al'	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
2.2			IBM_TDB	1
33 34	1	I and the second	USPAT	2003/01/23 09:57
34 35	1	1	USPAT	2003/01/23 09:57
36	1	•	USPAT	2003/01/23 09:57
49		'@ad<=20020109 and 'bonding pad' with	USPAT	2003/01/23 09:58
۷.	240	'integrated circuit' and 'Cu' and 'Al'	USPAT;	2003/01/23 10:02
		integrated circuit and cd and Ai	US-PGPUB; EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
50	231	(257/784).ccls. and @ad<=20020109 and	USPAT;	2003/01/23 10:38
1	1	'Copper' and 'aluminum'	US-PGPUB;	1
			EPO; JPO;	
1	ŀ		DERWENT;	!
! [ļ		IBM TDB	:
_	2054	(438/612).ccls. or (438/597).ccls. and	USPAT;	2003/01/23 08:44
i	÷	@ad<=20020109	US-PGPUB;	2000, 01, 00 00.11
1			EPO; JPO;	•
1			DERWENT;	
•	1		IBM TDB	1
. –	337	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	USPAT;	2002/08/21 11:04
		@ad<=20020109) and copper and aluminum	US-PGPUB;	1
!	j ·		EPO; JPO;	
			DERWENT;	ļ
	, ,	///20//610)	IBM_TDB	
-	/4	((438/612).ccls. or (438/597).ccls. and	USPAT;	2003/01/23 10:01
1	1	@ad<=20020109) and 'bonding pad' with	US-PGPUB;	
	:	'integrated circuit'	EPO; JPO;	
•	:	t.	DERWENT;	
_	1	((438/612).ccls. or (438/597).ccls. and	IBM_TDB USPAT;	2002/08/21 11:13
	_	@ad<=20020109) and Cu adj bonding adj pad	US-PGPUB;	2002/08/21 11:13
		with 'integrated circuit'	EPO; JPO;	i
		min integrated circuit	DERWENT;	
			IBM TDB	1
-	6	((438/612).ccls. or (438/597).ccls. and	USPAT;	2002/08/21 11:14
1	İ	(@ad<=20020109) and Copper adj bonding adj	US-PGPUB;	
		pad	EPO; JPO;	f ·
			DERWENT;	
			IBM_TDB	
-	1143		USPĀT;	2002/08/21 11:45
		with 'IMD' or 'intermetal dielectric'	US-PGPUB;	
			EPO; JPO;	
	-		DERWENT;	
_		82d<-20020100 and an air is	IBM_TDB	1
-	0	The state of any soliding pad	•	2002/08/21 11:27
		with 'IMD'	US-PGPUB;	
			EPO; JPO;	1
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1-	0	@ad<=20020109 and cu adj 'bonding pad'	IBM_TDB USPAT;	2002/00/21 11.27
	i	with 'intermetal dielectric'	US-PGPUB;	2002/08/21 11:27
		THEORIGINAL GLOSGELLE	EPO; JPO;	
j i			DERWENT;	
			IBM TDB	: 1
-	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/01/23 09:03
		with 'Al'	US-PGPUB;	1
]			EPO; JPO;	<u> </u>
	11		DERWENT;	1
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· = ·] 3	[@ad<=20020109 and cu adj 'bonding pad' and 'IMD'	USPAT; US-PGPUB; EPO; JPO;	2002/08/21 13	l:43
-	1	"3942245".PN. "5075965".PN. "5288006".PN. "5376235".PN. "5384284".PN. "5436412".PN.	DERWENT; IBM_TDB USPAT USPAT USPAT USPAT USPAT	2002/08/21 11 2002/08/21 11 2002/08/21 11 2002/08/21 11 2002/08/21 11	1:40 1:40 1:41 1:41
-		@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11 2002/08/21 11	
:	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11	l:46
!	809 	(228/180.21).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11	.:48
-	93	((228/180.21).CCLS.) and bonding adj pad	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11	.:50
-	9	((228/180.21).CCLS.) and bonding adj pad with copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 13	:32
	8	((228/180.21).CCLS.) and bond adj pad with copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 13	:30
-	. 0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 08	:45
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 13	:31
-	639	@ad<=20010119 and bonding adj pad with copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 13	:36
-	359	@ad<=20010119 and bonding adj pad with copper and aluminum	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	: 2002/08/21 13 	: 47
-	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 13	:59
-	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14	:00

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4120 'bonding pad' and apparatus	USPAT; 2002/08/21 15:03 US-PGPUB; EPO; JPO;
3573 ((257/459) or (257/676) or (257/786) or (275/670) or (257/672)).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB